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amended

a heat dissipation element thermally connected to said mounting plate and being spaced from said circuit board, said heat dissipating element being disposed in a position to receive air flow on both sides; and

a heat generating component mounted on said mounting plate at a second major surface opposite said first major surface.

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13. (Amended) A heat sink for a surface mounted heat generating component, comprising:

a mounting plate of a generally planar configuration defining a plurality of openings therethrough for adhesive flow through said openings;

an extension member extending generally perpendicular to said mounting plate;

a heat dissipation element connected to said extension member, said heat dissipation element and said extension member surface and said mounting plate being thermally conductive and said heat dissipating element being spaced from the heat generating component.

Add new claim 14 as follows:

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14. A surface mountable heat sink for a component, comprising:

a substantially planar mounting plate having an outer extent substantially a same shape and dimensions as a footprint of the component, said mounting plate defining opening extending therethrough;

a vertical portion extending at a substantially right angle from said mounting plate, said vertical portion having a first end at said mounting plate and a second end opposite said first end; and

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cont a heat dissipating fin connected to said second end of said vertical portion, said heat dissipating fin having an extent in a direction substantially parallel to said mounting plate and space therefrom, said heat dissipating fin being spaced from the component when the component is mounted on said mounting plate.

15. A surface mountable heat sink and component as claimed in 14, further comprising:

a channel between said mounting plate and said vertical portion, said channel receiving a portion of the component when the component is mounted on said mounting plate.

16. A power transistor mounting, comprising:

a power transistor component having a housing and leads and a back plate, said back plate having an edge portion extending beyond said housing;

a perforate plate disposed against said back plate of said power transistor;

a channel connected to said perforate plate, said channel engaging said edge portion of said back plate;

a vertical portion extending from said channel in a direction substantially perpendicular to said perforate plate, said vertical portion having a first end at said channel and a second end opposite said first end; and

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a heat dissipating fin connected to said second end of said vertical portion, said heat  
dissipating fin including a planar part substantially parallel to said perforate  
plate and spaced from said power transistor to receive an air flow;  
said perforate plate and said channel and said vertical portion and said heat dissipating fin  
being formed of a heat conducting material to dissipate heat generated by the  
power transistor.

17. A heat sink, comprising:

a unitary sheet of thermally conductive metallic material formed to include:

a mounting plate having a planar configuration, said mounting plate defining  
perforations extending therethrough, said mounting plate having a first  
connecting edge;

a connecting portion extending from said first connecting edge of said mounting plate,  
said connecting portion being disposed substantially perpendicular to said  
mounting plate, said connecting portion having a second connecting edge  
spaced from said first connecting edge; and

a heat dissipating portion defining heat dissipating surfaces.